

Title (en)
Modular connector system.

Title (de)
Verbindersystem in Modultechnik.

Title (fr)
Système de connecteur modulaire.

Publication
EP 0437035 A2 19910717 (EN)

Application
EP 90312923 A 19901128

Priority
US 46358690 A 19900111

Abstract (en)
An electrical connector has several rows of contacts connected to two rows of leads that engage terminals on a circuit board assembly, which enables a large number of contacts to be located in a connector of moderate cost. A connector insert comprises a wafer device and multiple leads, the leads having front lead portions connected to multiple rows of contacts on the wafer device, middle lead portions moulded into the wafer device, and rearward lead portions lying in two parallel rows for contacting terminals on opposite sides of the circuit board assembly. Each wafer device includes two substantially identical wafers, to allow moulding of a single row of leads at a time into a wafer. Each wafer has forwardly projecting towers that each lie around the front portion of a lead, and each contact has a periphery captured by a tower portion and a hole that receives a lead front portion. The contacts are arranged in columns on the wafer device, with at least four contacts in each column, and some of the lead middle portions extend both laterally and longitudinally to provide a small spacing or pitch of the lead rear portions. The insert has leaf springs at opposite sides for centering the insert in the connector housing while allowing the insert to "float" within the housing. <IMAGE>

IPC 1-7
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IPC 8 full level
H01R 12/18 (2006.01); **H01R 12/50** (2011.01); **H01R 12/73** (2011.01); **H01R 43/24** (2006.01); **H01R 4/02** (2006.01); **H01R 13/405** (2006.01); **H01R 13/508** (2006.01)

CPC (source: EP)
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Cited by
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